



DATA SHEET

SEMICONDUCTOR

RB751G-40

Schottky barrier diode

●Applications

General rectification

●Features

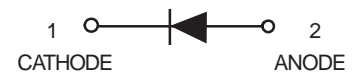
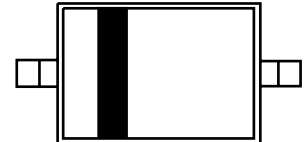
- 1) Small power mold type.
(SOD-723)
- 2) Low V_F
- 3) High reliability
- 4) Pb-Free package is available

●Construction

Silicon epitaxial planar



SOD-723



●Absolute maximum ratings ($T_a=25^{\circ}\text{C}$)

| Parameter | Symbol | Limits | Unit |
|--|-----------|-------------|--------------------|
| Reverse voltage (repetitive peak) | V_{RM} | 40 | V |
| Reverse voltage (DC) | V_R | 30 | V |
| Average rectified forward current | I_o | 30 | mA |
| Forward current surge peak (60Hz~1cyc) | I_{FSM} | 200 | mA |
| Junction temperature | T_j | 125 | $^{\circ}\text{C}$ |
| Storage temperature | T_{stg} | -40 to +125 | $^{\circ}\text{C}$ |

●Electrical characteristic ($T_a=25^{\circ}\text{C}$)

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Conditions |
|-------------------------------|--------|------|------|------|---------------|-----------------------------------|
| Forward voltage | V_F | - | - | 0.37 | V | $I_F=1\text{mA}$ |
| Reverse current | I_R | - | - | 0.5 | μA | $V_R=30\text{V}$ |
| Capacitance between terminals | C_t | - | 2 | - | pF | $V_R=1\text{V}$, $f=1\text{MHz}$ |

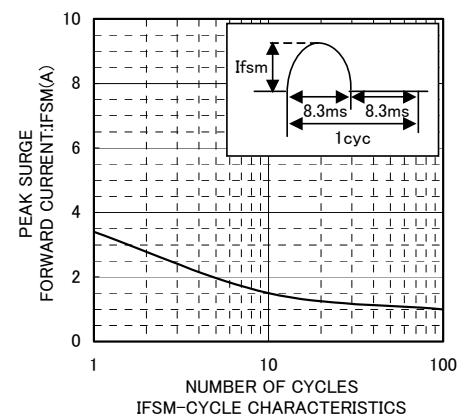
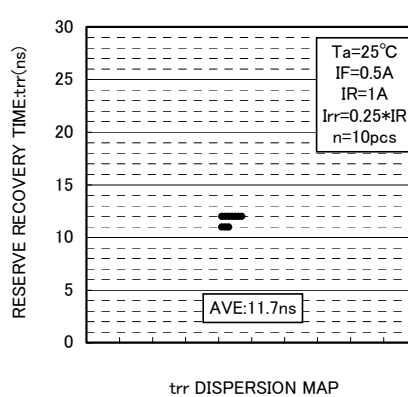
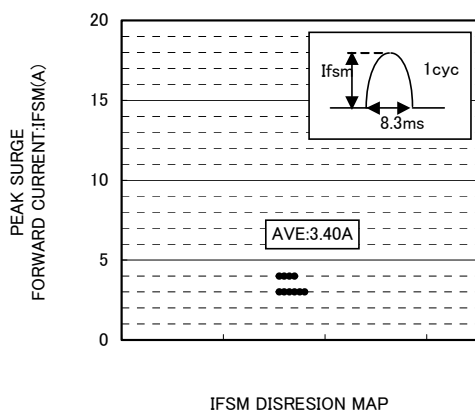
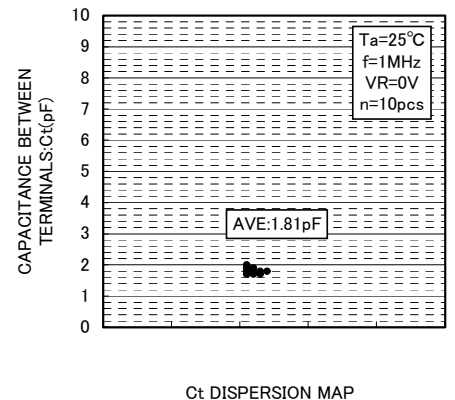
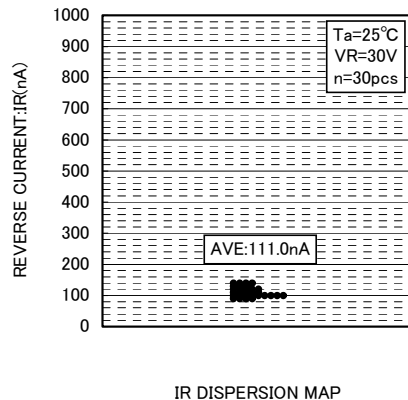
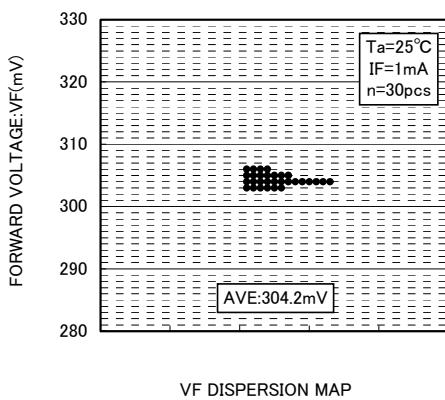
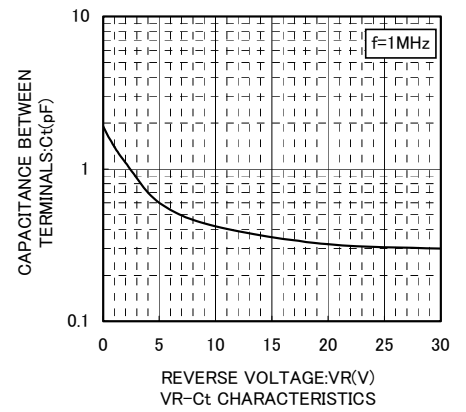
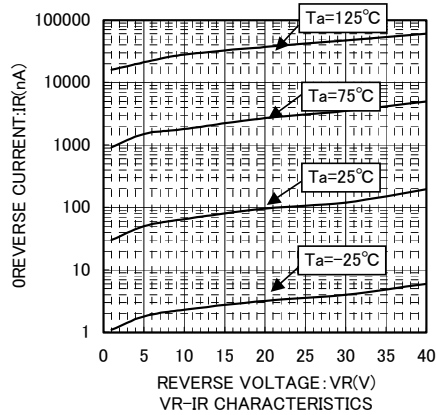
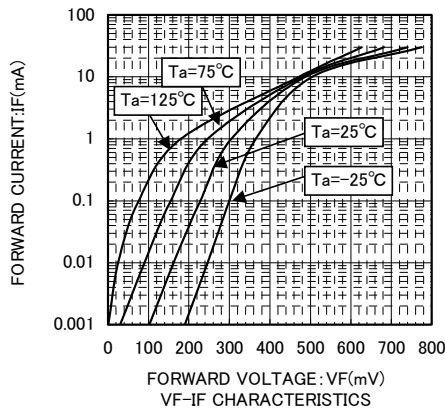
●DEVICE MARKING AND ORDERING INFORMATION

| Device | Marking | Shipping |
|-----------|---------|----------------|
| RB751G-40 | 5 | 3000/Tape&Reel |

DEVICE CHARACTERISTICS

RB751G-40

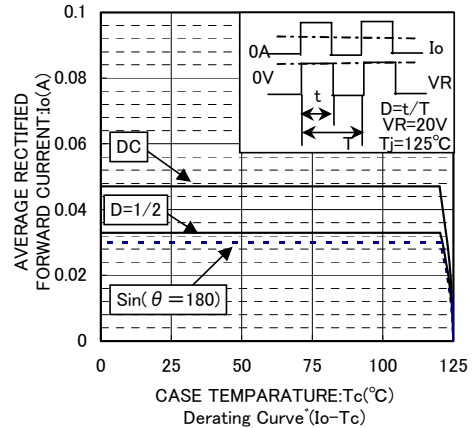
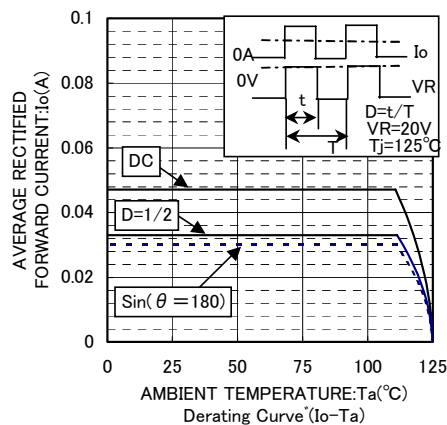
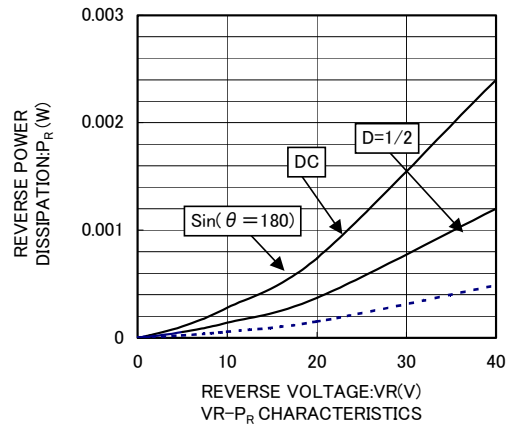
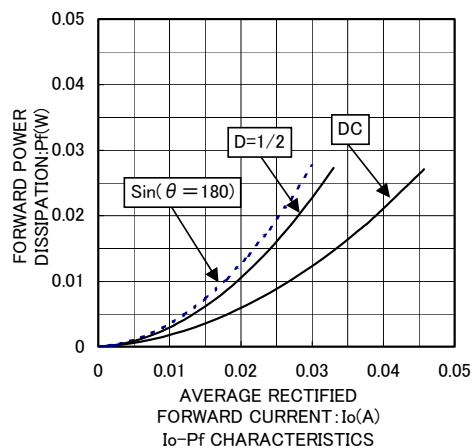
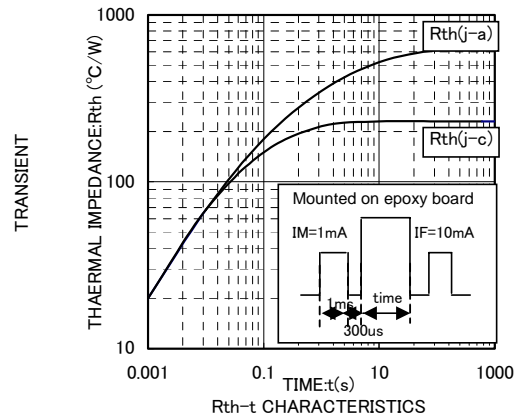
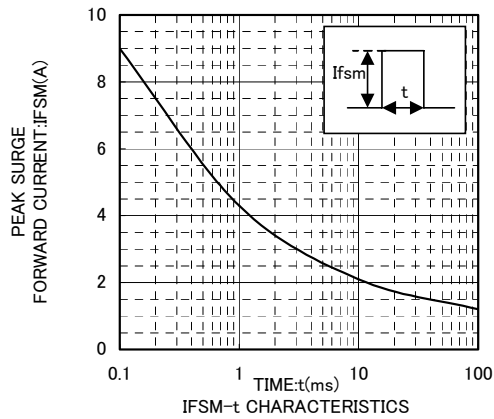
Electrical characteristic curves (Ta=25°C)



DEVICE CHARACTERISTICS

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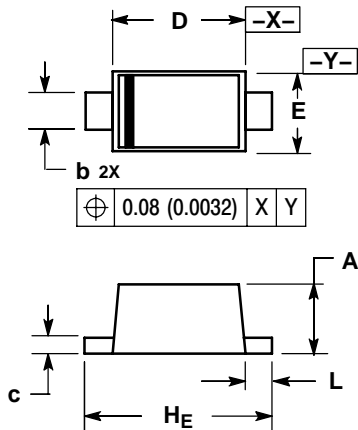
Electrical characteristic curves ($T_a=25^{\circ}\text{C}$)



PACKAGE OUTLINE & DIMENSIONS

RB751G-40

SOD-723



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

| DIM | MILLIMETERS | | | INCHES | | |
|----------------|-------------|------|------|--------|--------|--------|
| | MIN | NOM | MAX | MIN | NOM | MAX |
| A | 0.49 | 0.52 | 0.55 | 0.019 | 0.020 | 0.022 |
| b | 0.25 | 0.28 | 0.32 | 0.0098 | 0.011 | 0.013 |
| c | 0.08 | 0.12 | 0.15 | 0.0032 | 0.0047 | 0.0059 |
| D | 0.95 | 1.00 | 1.05 | 0.037 | 0.039 | 0.041 |
| E | 0.55 | 0.60 | 0.65 | 0.022 | 0.024 | 0.026 |
| H _E | 1.35 | 1.40 | 1.45 | 0.053 | 0.055 | 0.057 |
| L | 0.15 | 0.20 | 0.25 | 0.006 | 0.0079 | 0.010 |

SOLDERING FOOTPRINT*

